

3-Level NPC Inverter Module

Product Preview

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

The NXH600N105L7F5S2HG/P2HG is a power module in F5BP package containing an I-type neutral point clamped three-level inverter. The integrated field stop trench IGBTs and FRDs provide lower conduction and switching losses, enabling designers to achieve high efficiency, high power density and superior reliability.

Features

- I-type Neutral Point Clamped Three-level Inverter Module
- 1050 V Field Stop 7 IGBTs
- Low Inductive Layout
- Solder Pins and Press Fit Pins
- Integrated NTC Thermistor
- This is a Pb-Free and Halide Free Device

Typical Applications

- Energy Storage System
- Solar Inverters
- Uninterruptable Power Supplies Systems

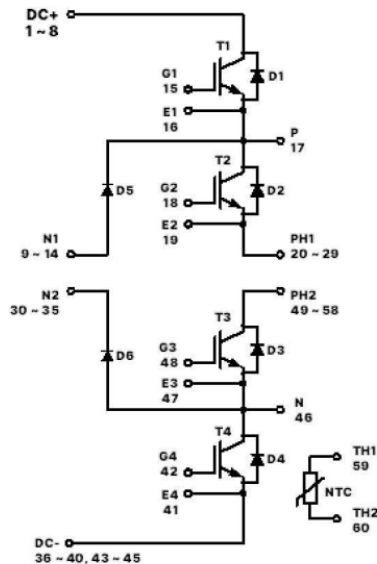
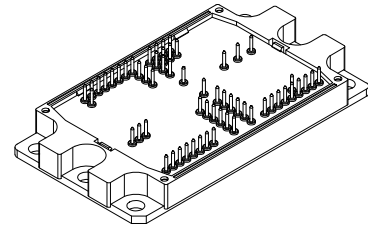
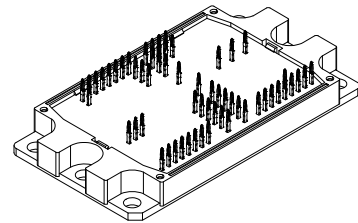


Figure 1. NXH600N105L7F5S2HG/P2HG Schematic

This document contains information on a product under development. onsemi reserves the right to change or discontinue this product without notice.

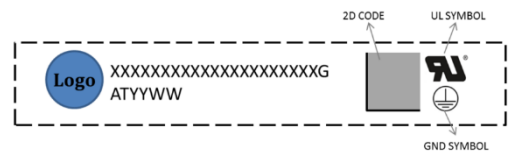


PIM60 112x62 (SOLDER PIN)
CASE 180CY



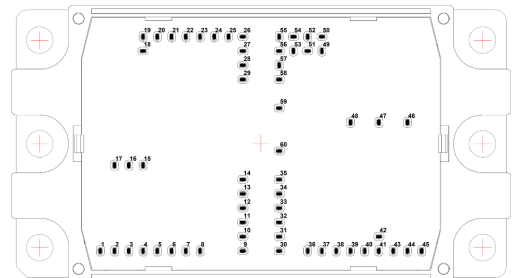
PIM60 112x62 (PRESS FIT PIN)
CASE 180HY

MARKING DIAGRAM



XXXXXX = Device Code
G = Pb-Free Package
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

PIN CONNECTIONS



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

MODULE CHARACTERISTICS

Parameter	Symbol	Value	Unit
Operating Temperature under Switching Condition	T_{VJOP}	-40 to 150	°C
Storage Temperature Range	T_{stg}	-40 to 125	°C
Isolation Test Voltage, $t = 2$ sec, 50 Hz (Note 1)	V_{is}	4800	V_{RMS}
Stray Inductance	$L_{s\ CE}$	15	nH
Terminal Connection Torque (M5, Screw)	M	3 to 5	Nm
Weight	G	245	g
Creepage Distance (terminal to heatsink)		17.46	mm
Creepage Distance (terminal to terminal)		6.48	mm
Clearance Distance (terminal to heatsink)		15.62	mm
Clearance Distance (terminal to terminal)		5.05	mm
Comparative Tracking Index	CTI	>600	

1. 4800 VAC_{RMS} for 2 second duration is equivalent to 4000 VAC_{RMS} for 1 minute duration.

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Max	Unit
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OUTER IGBT (T1, T4)

Collector-Emitter Voltage	V_{CES}	1050	V
Gate-Emitter Voltage Positive Transient Gate-emitter Voltage ($T_{pulse} = 5\ \mu\text{s}$, $D < 0.10$)	V_{GE}	± 20 30	V
Continuous Collector Current @ $T_c = 80^\circ\text{C}$ ($T_J = 175^\circ\text{C}$)	I_C	429	A
Pulsed Peak Collector Current @ $T_c = 80^\circ\text{C}$ ($T_J = 175^\circ\text{C}$) @ $T_{pulse} = 1\ \text{ms}$	$I_{C(Pulse)}$	1287	A
Power Dissipation ($T_J = 175^\circ\text{C}$, $T_c = 80^\circ\text{C}$)	P_{tot}	1080	W
Minimum Operating Junction Temperature	T_{JMIN}	-40	°C
Maximum Operating Junction Temperature	T_{JMAX}	175	°C

INNER IGBT (T2, T3)

Collector-Emitter Voltage	V_{CES}	1050	V
Gate-Emitter Voltage Positive Transient Gate-emitter Voltage ($T_{pulse} = 5\ \mu\text{s}$, $D < 0.10$)	V_{GE}	± 20 30	V
Continuous Collector Current @ $T_c = 80^\circ\text{C}$ ($T_J = 175^\circ\text{C}$)	I_C	433	A
Pulsed Peak Collector Current @ $T_c = 80^\circ\text{C}$ ($T_J = 175^\circ\text{C}$) @ $T_{pulse} = 1\ \text{ms}$	$I_{C(Pulse)}$	1299	A
Power Dissipation ($T_J = 175^\circ\text{C}$, $T_c = 80^\circ\text{C}$)	P_{tot}	1080	W
Minimum Operating Junction Temperature	T_{JMIN}	-40	°C
Maximum Operating Junction Temperature	T_{JMAX}	175	°C

NEUTRAL POINT DIODE (D5, D6)

Peak Repetitive Reverse Voltage	V_{RRM}	1050	V
Continuous Forward Current @ $T_c = 80^\circ\text{C}$	I_F	180	A
Repetitive Peak Forward Current ($T_J = 175^\circ\text{C}$) $T_{pulse} = 1\ \text{ms}$	I_{FRM}	540	A
Maximum Power Dissipation @ $T_c = 80^\circ\text{C}$ ($T_J = 175^\circ\text{C}$)	P_{tot}	426	W
Minimum Operating Junction Temperature	T_{JMIN}	-40	°C
Maximum Operating Junction Temperature	T_{JMAX}	175	°C

INVERSE DIODES (D1, D2, D3, D4)

Peak Repetitive Reverse Voltage	V_{RRM}	1050	V
Continuous Forward Current @ $T_c = 80^\circ\text{C}$	I_F	196	A

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MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Max	Unit
INVERSE DIODES (D1, D2, D3, D4)			
Repetitive Peak Forward Current (T _J = 175°C) @ T _{pulse} = 1 ms	I _{FRM}	588	A
Maximum Power Dissipation @ T _c = 80°C (T _J = 175°C)	P _{tot}	434	W
Minimum Operating Junction Temperature	T _{JMIN}	-40	°C
Maximum Operating Junction Temperature	T _{JMAX}	175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe Operating parameters.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
OUTER IGBT (T1, T4)						
Collector-Emitter Cutoff Current	V _{GE} = 0 V, V _{CE} = 1050 V	I _{CES}	–	–	500	μA
Collector-Emitter Saturation Voltage	V _{GE} = 15 V, I _C = 600 A, T _J = 25°C	V _{CE(SAT)}	–	1.6	2.3	V
	V _{GE} = 15 V, I _C = 600 A, T _J = 150°C		–	2.0	–	
Gate-Emitter Threshold Voltage	V _{GE} = V _{CE} , I _C = 600 mA	V _{GE(TH)}	4.0	5.5	6.9	V
Gate Leakage Current	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	–	–	1	μA
Internal Gate Resistor		R _g	–	0.58	–	Ω
Turn-off safe operating area	V _{CC} < 800 V, R _{G,off} ≥ 30 Ω, T _{vj} < 150°C		–	800	–	A
Turn-on Delay Time	T _J = 25°C V _{CE} = 600 V, I _C = 200 A V _{GE} = -9 V to +15 V, R _{G,on} = 7 Ω, R _{G,off} = 23 Ω	t _{d(on)}	–	230	–	ns
Rise Time		t _r	–	46	–	
Turn-off Delay Time		t _{d(off)}	–	1582	–	
Fall Time		t _f	–	16.7	–	
Turn-on Switching Loss per Pulse		E _{on}	–	8810	–	μJ
Turn off Switching Loss per Pulse		E _{off}	–	8550	–	
Turn-on Delay Time	T _J = 125°C V _{CE} = 600 V, I _C = 200 A V _{GE} = -9 V to +15 V, R _{G,on} = 7 Ω, R _{G,off} = 23 Ω	t _{d(on)}	–	206	–	ns
Rise Time		t _r	–	50	–	
Turn-off Delay Time		t _{d(off)}	–	1702	–	
Fall Time		t _f	–	15.6	–	
Turn-on Switching Loss per Pulse		E _{on}	–	13390	–	μJ
Turn off Switching Loss per Pulse		E _{off}	–	10990	–	
Input Capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 100 kHz	C _{ies}	–	48843	–	pF
Output Capacitance		C _{oes}	–	1767	–	
Reverse Transfer Capacitance		C _{res}	–	281	–	
Total Gate Charge	V _{CE} = 600 V, I _C = 57 A, V _{GE} = -15/+20 V	Q _g	–	2988	–	nC
Thermal Resistance – Chip-to-heatsink	Thermal grease, Thickness = 2 Mil ±2%, λ = 2.87 W/mK	R _{thJH}	–	0.139	–	°C/W
Thermal Resistance – Chip-to-case		R _{thJC}	–	0.088	–	°C/W

NEUTRAL POINT DIODE (D5, D6)

Diode Forward Voltage	I _F = 300 A, T _J = 25°C	V _F	–	2.6	3.4	V
	I _F = 300 A, T _J = 150°C		–	2.4	–	

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ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
NEUTRAL POINT DIODE (D5, D6)						
Reverse Recovery Time	$T_J = 25^{\circ}\text{C}$ $V_{CE} = 600\text{ V}$, $I_C = 200\text{ A}$ $V_{GE} = -9\text{ V}$ to $+15\text{ V}$, $R_{G,on} = 7\ \Omega$	t_{rr}	–	93	–	ns
Reverse Recovery Charge		Q_{rr}	–	6321	–	nC
Peak Reverse Recovery Current		I_{RRM}	–	161	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	3.56	–	A/ μs
Reverse Recovery Energy		E_{rr}	–	1724	–	μJ
Reverse Recovery Time	$T_J = 125^{\circ}\text{C}$ $V_{CE} = 600\text{ V}$, $I_C = 200\text{ A}$ $V_{GE} = -9\text{ V}$ to $+15\text{ V}$, $R_{G,on} = 7\ \Omega$	t_{rr}	–	169	–	ns
Reverse Recovery Charge		Q_{rr}	–	17552	–	nC
Peak Reverse Recovery Current		I_{RRM}	–	245	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	3.32	–	A/ μs
Reverse Recovery Energy		E_{rr}	–	7229	–	μJ
Thermal Resistance – Chip-to-heatsink	Thermal grease, Thickness = 2 Mil $\pm 2\%$, $\lambda = 2.87\text{ W/mK}$	R_{thJH}	–	0.327	–	$^{\circ}\text{C/W}$
Thermal Resistance – Chip-to-case		R_{thJC}	–	0.223	–	$^{\circ}\text{C/W}$
INNER IGBT (T2, T3)						
Collector-Emitter Cutoff Current	$V_{GE} = 0\text{ V}$, $V_{CE} = 1050\text{ V}$	I_{CES}	–	–	500	μA
Collector-Emitter Saturation Voltage	$V_{GE} = 15\text{ V}$, $I_C = 600\text{ A}$, $T_J = 25^{\circ}\text{C}$	$V_{CE(sat)}$	–	1.6	2.3	V
	$V_{GE} = 15\text{ V}$, $I_C = 600\text{ A}$, $T_J = 150^{\circ}\text{C}$		–	2.0	–	
Gate-Emitter Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 600\text{ mA}$	$V_{GE(TH)}$	4.0	5.5	6.9	V
Gate Leakage Current	$V_{GE} = 20\text{ V}$, $V_{CE} = 0\text{ V}$	I_{GES}	–	0.02	1	μA
Internal Gate Resistor		R_g	–	0.58	–	Ω
Turn-off safe operating area	$V_{CC} < 800\text{ V}$, $R_{G,off} \geq 35\ \Omega$, $T_{vj} < 150^{\circ}\text{C}$		–	800	–	A
Turn-on Delay Time	$T_J = 25^{\circ}\text{C}$ $V_{CE} = 600\text{ V}$, $I_C = 200\text{ A}$ $V_{GE} = -9\text{ V}$ to $+15\text{ V}$, $R_{G,on} = 7\ \Omega$, $R_{G,off} = 31\ \Omega$	$t_{d(on)}$	–	233	–	ns
Rise Time		t_r	–	57	–	
Turn-off Delay Time		$t_{d(off)}$	–	2200	–	
Fall Time		t_f	–	17.9	–	
Turn-on Switching Loss per Pulse		E_{on}	–	8640	–	μJ
Turn off Switching Loss per Pulse		E_{off}	–	11800	–	
Turn-on Delay Time	$T_J = 125^{\circ}\text{C}$ $V_{CE} = 600\text{ V}$, $I_C = 200\text{ A}$ $V_{GE} = -9\text{ V}$ to $+15\text{ V}$, $R_{G,on} = 7\ \Omega$, $R_{G,off} = 31\ \Omega$	$t_{d(on)}$	–	210	–	ns
Rise Time		t_r	–	62	–	
Turn-off Delay Time		$t_{d(off)}$	–	2350	–	
Fall Time		t_f	–	18.1	–	
Turn-on Switching Loss per Pulse		E_{on}	–	12510	–	μJ
Turn off Switching Loss per Pulse		E_{off}	–	14500	–	
Input Capacitance	$V_{CE} = 20\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 100\text{ kHz}$	C_{ies}	–	47927	–	pF
Output Capacitance		C_{oes}	–	1871	–	
Reverse Transfer Capacitance		C_{res}	–	304	–	
Total Gate Charge	$V_{CE} = 600\text{ V}$, $I_C = 57\text{ A}$, $V_{GE} = -15/+20\text{ V}$	Q_g	–	2940	–	nC
Thermal Resistance – Chip-to-heatsink	Thermal grease, Thickness = 2 Mil $\pm 2\%$, $\lambda = 2.87\text{ W/mK}$	R_{thJH}	–	0.139	–	$^{\circ}\text{C/W}$
Thermal Resistance – Chip-to-case		R_{thJC}	–	0.088	–	$^{\circ}\text{C/W}$

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
INVERSE DIODES (D1, D2, D3, D4)						
Diode Forward Voltage	I _F = 300 A, T _J = 25°C	V _F	–	2.5	3.4	V
	I _F = 300 A, T _J = 150°C		–	2.3	–	
Reverse Recovery Time	T _J = 25°C V _{CE} = 600 V, I _C = 200 A V _{GE} = -9 V to +15 V, R _{G,on} = 7 Ω	t _{rr}	–	89	–	ns
Reverse Recovery Charge		Q _{rr}	–	5580	–	nC
Peak Reverse Recovery Current		I _{RRM}	–	135	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	2.81	–	A/μs
Reverse Recovery Energy		E _{rr}	–	1664	–	μJ
Reverse Recovery Time	T _J = 125°C V _{CE} = 600 V, I _C = 200 A V _{GE} = -9 V to +15 V, R _{G,on} = 7 Ω	t _{rr}	–	182	–	ns
Reverse Recovery Charge		Q _{rr}	–	16903	–	nC
Peak Reverse Recovery Current		I _{RRM}	–	201	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	2.62	–	A/μs
Reverse Recovery Energy		E _{rr}	–	6485	–	μJ
Thermal Resistance – Chip-to-heatsink	Thermal grease, Thickness = 2 Mil ±2%, λ = 2.87 W/mK	R _{thJH}	–	0.277	–	°C/W
Thermal Resistance – Chip-to-case		R _{thJC}	–	0.219	–	°C/W

THERMISTOR CHARACTERISTICS

Nominal Resistance	T = 25°C	R ₂₅	–	5	–	kΩ
Nominal Resistance	T = 100°C	R ₁₀₀	–	492.2	–	Ω
Deviation of R25		R/R	-1	–	1	%
Power Dissipation		P _D	–	5	–	mW
Power Dissipation Constant			–	1.3	–	mW/K
B-value	B(25/85), tolerance ±1%		–	3430	–	K

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Device	Marking	Package	Shipping
NXH600N105L7F5S2HG	NXH600N105L7F5S2HG	F5 – PIM60 112x62 (SOLDER PIN) (Pb-Free and Halide-Free)	8 Units / Blister Tray
NXH600N105L7F5P2HG	NXH600N105L7F5P2HG	F5 – PIM60 112x62 (PRESS FIT PIN) (Pb-Free and Halide-Free)	8 Units / Blister Tray

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – IGBT T1/T4 AND D5/D6 DIODE

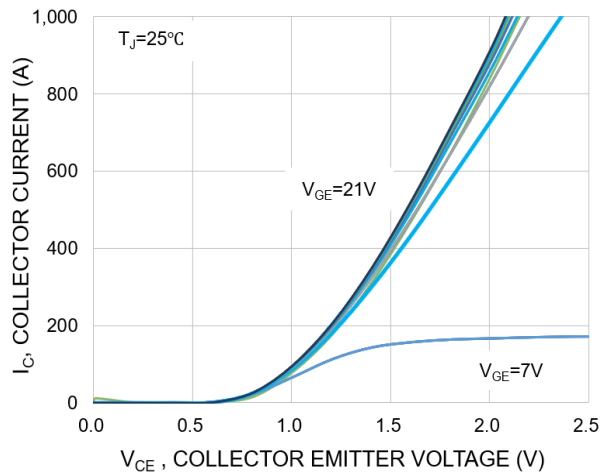


Figure 2. Typical Output Characteristics – IGBT

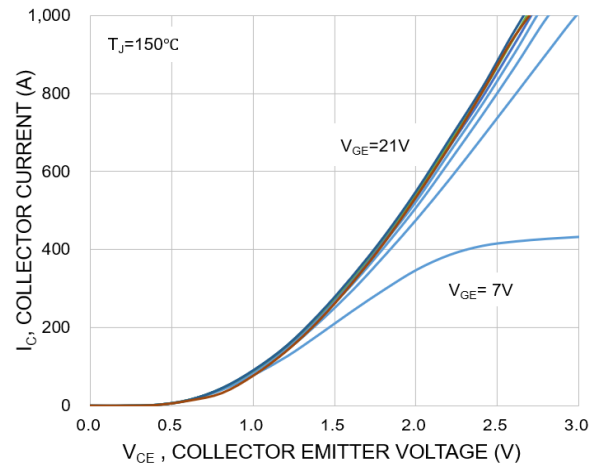


Figure 3. Typical Output Characteristics – IGBT

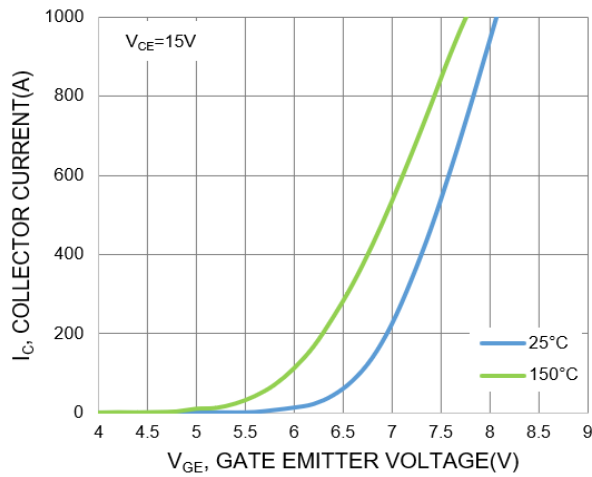


Figure 4. Transfer Characteristics – IGBT

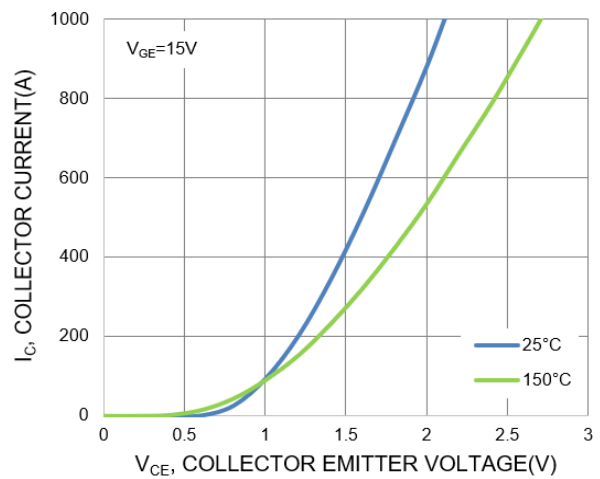


Figure 5. Saturation Voltage Characteristic – IGBT

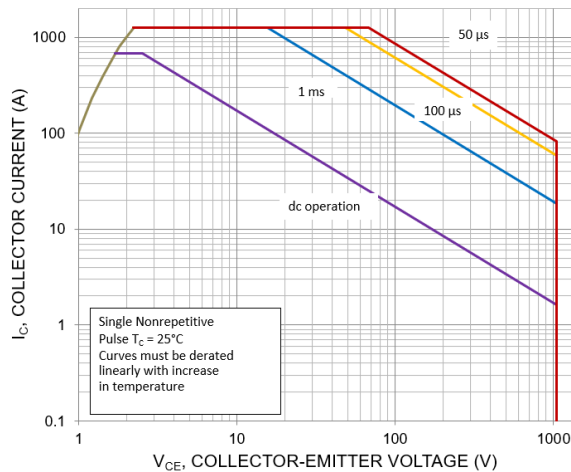


Figure 6. FBSOA

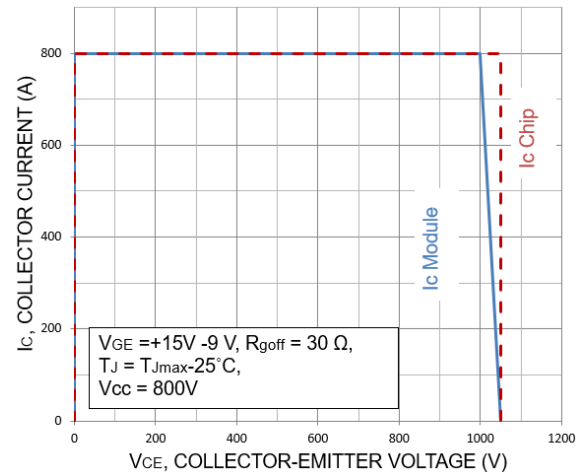


Figure 7. RBSOA

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – IGBT T1/T4 AND D5/D6 DIODE

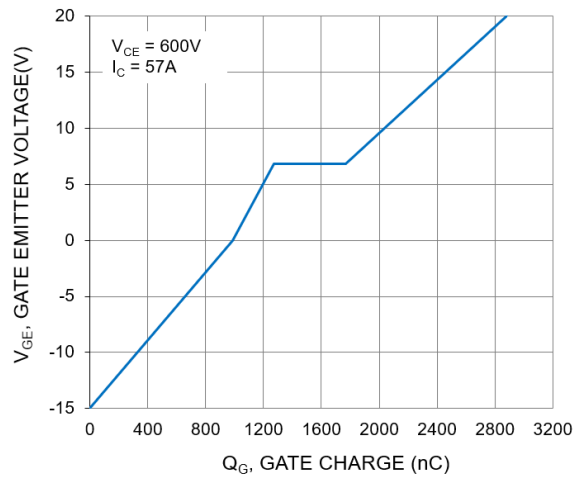


Figure 8. Gate Voltage vs. Gate Charge

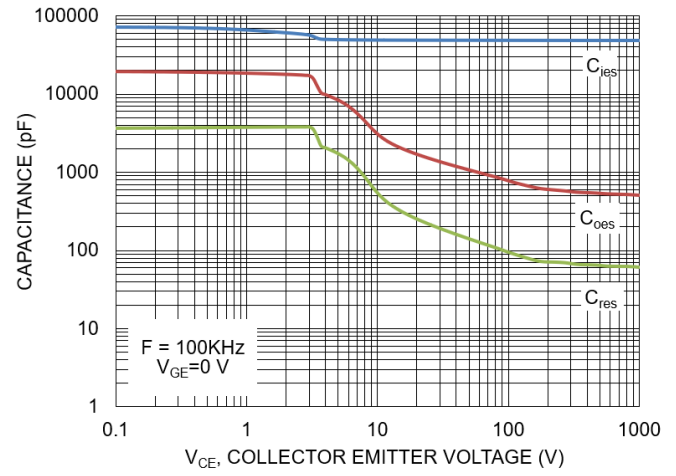


Figure 9. Capacitance

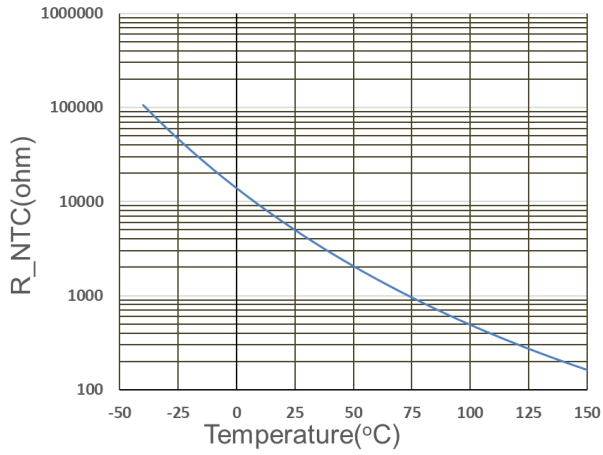


Figure 10. Temperature vs. NTC Value

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – IGBT T2/T3 AND D3/D4, D1/D2 DIODE

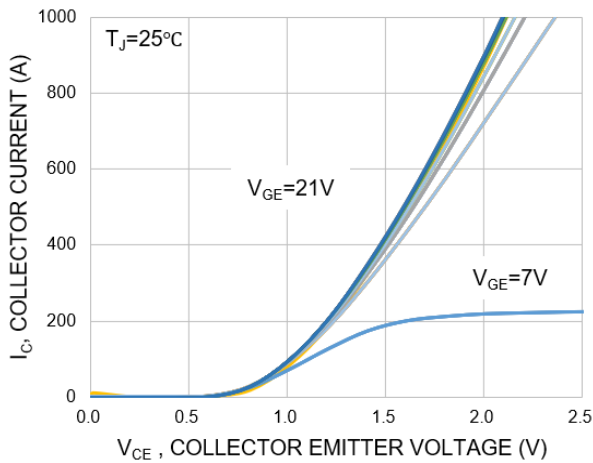


Figure 11. Typical Output Characteristics

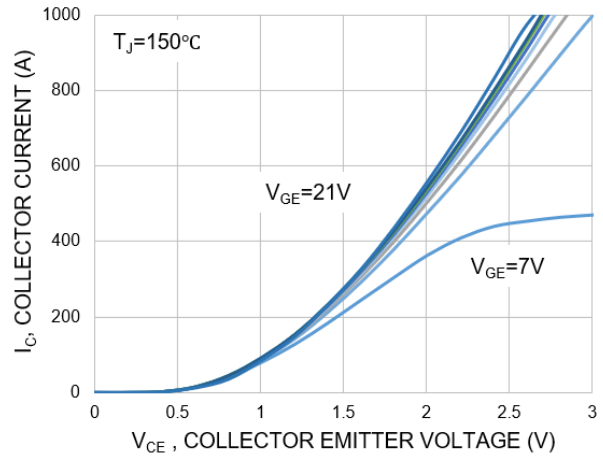


Figure 12. Typical Output Characteristics

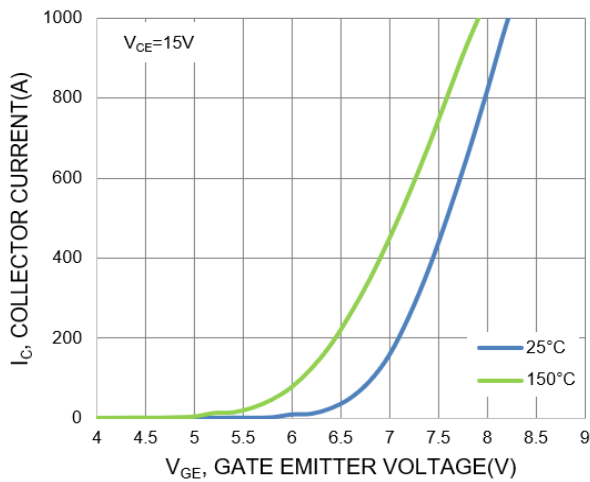


Figure 13. Transfer Characteristics – IGBT

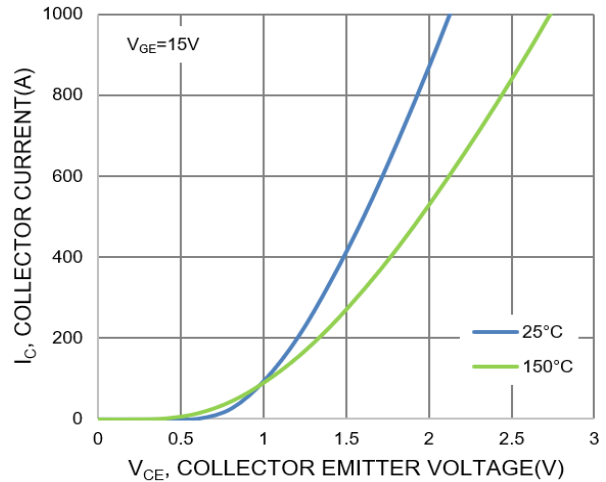


Figure 14. Saturation Voltage Characteristic – IGBT

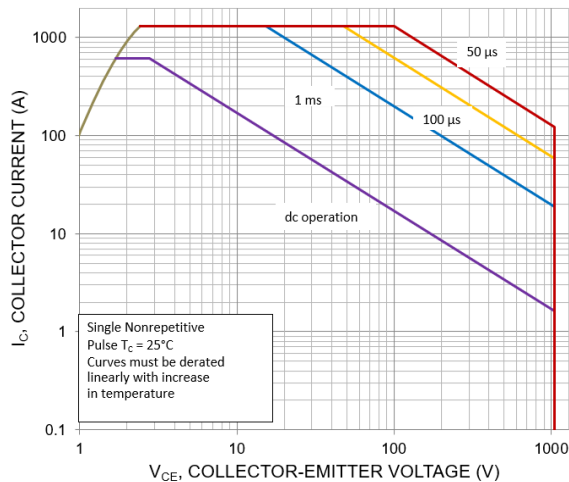


Figure 15. FBSOA

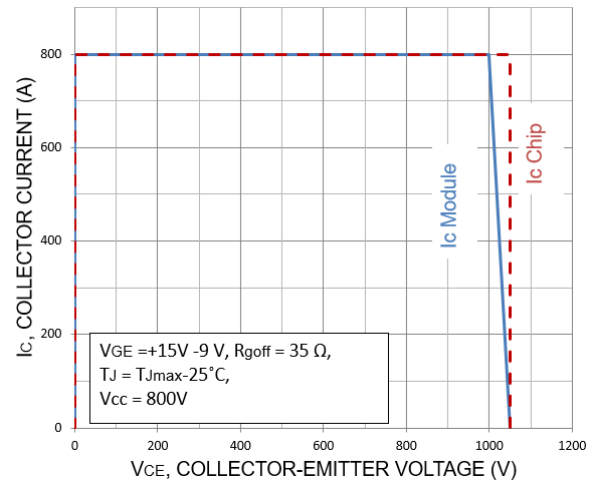


Figure 16. RBSOA

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – IGBT T2/T3 AND D3/D4, D1/D2 DIODE

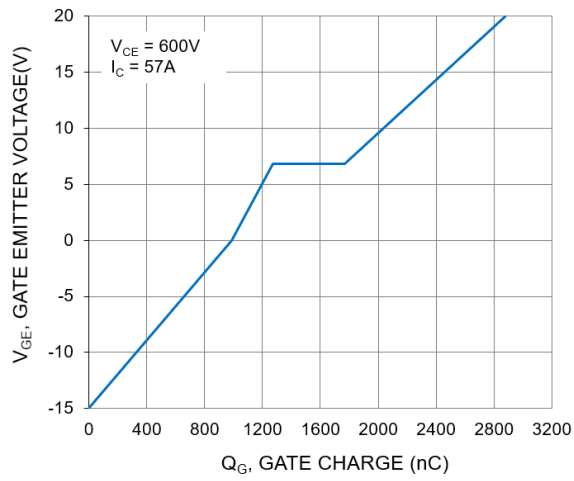


Figure 17. Gate Voltage vs. Gate Charge

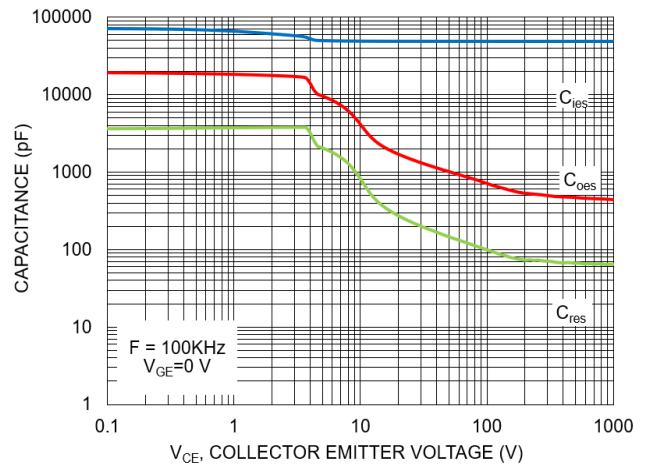


Figure 18. Capacitance

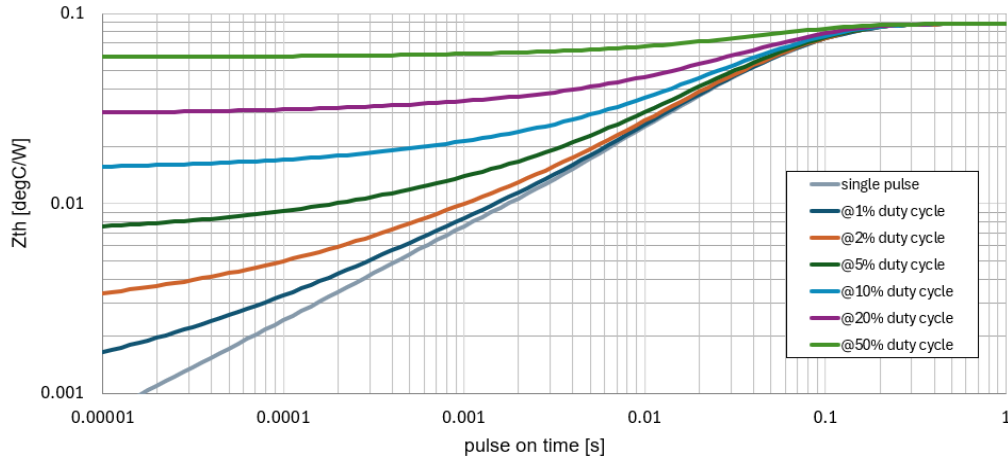


Figure 19. Transient Thermal Impedance (IGBT Z_{thjc})

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – D1/D2/D3/D4 (INVERSE DIODE)

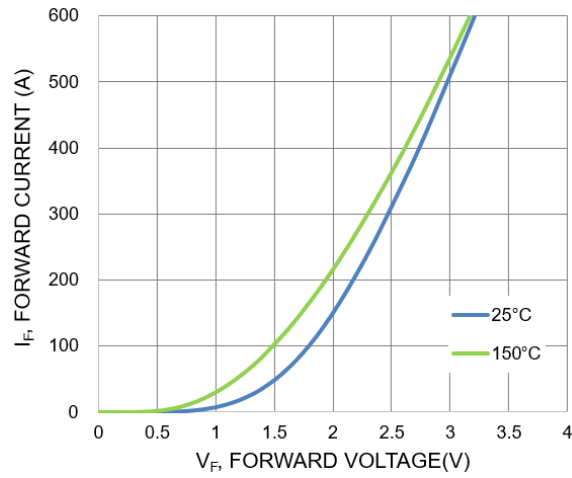


Figure 20. Inverse Diode Forward Characteristics

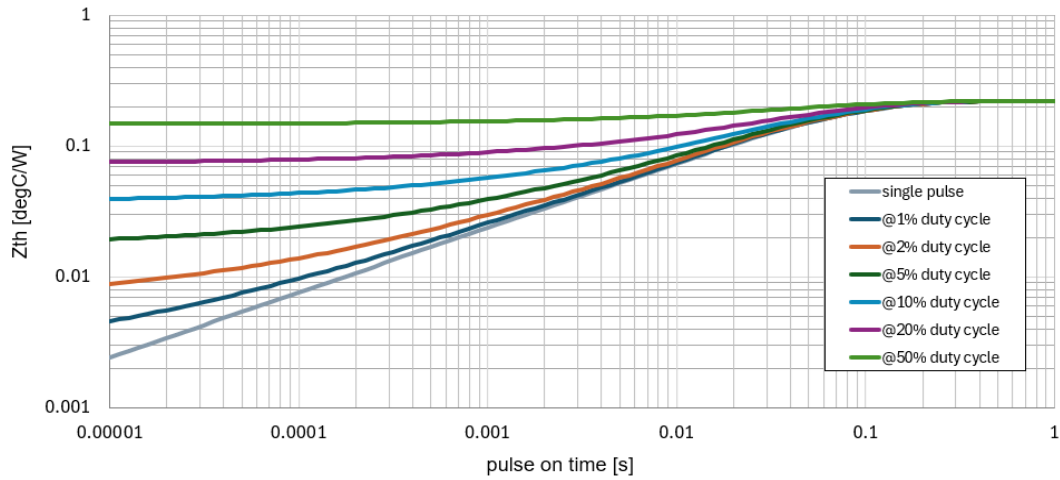


Figure 21. Transient Thermal Impedance (Inverse Diode Z_{thjc})

TYPICAL CHARACTERISTICS – D5, D6 (NEUTRAL POINT DIODE)

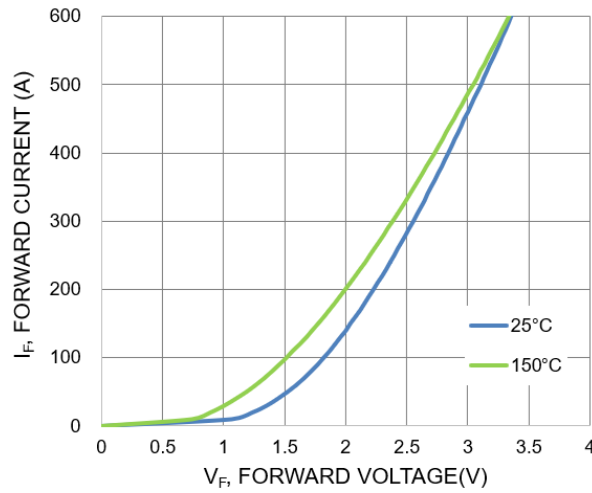


Figure 22. Neutral Point Diode Forward Characteristics

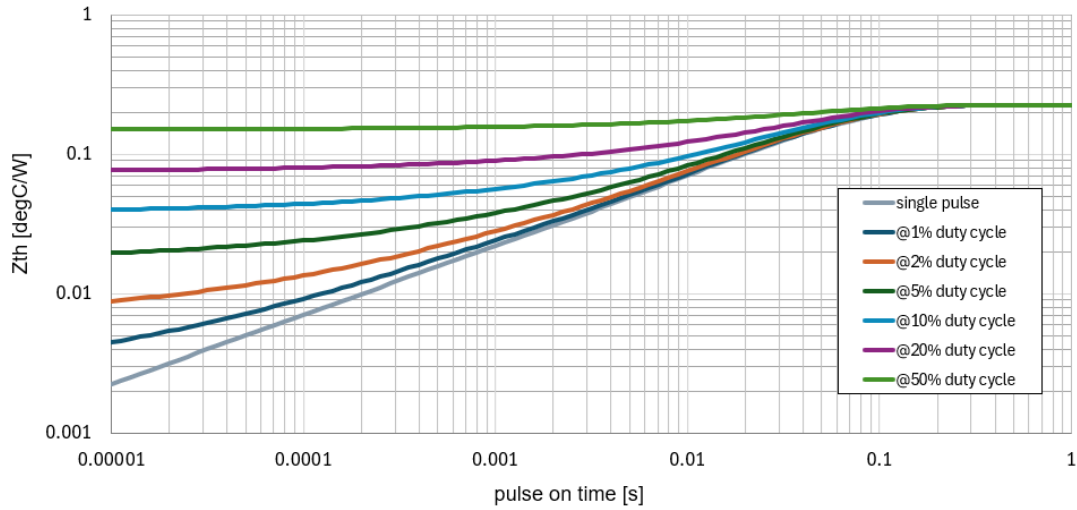


Figure 23. Transient Thermal Impedance (Neutral Point Diode Z_{thjc})

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – T1 || D5 OR T4 || D6

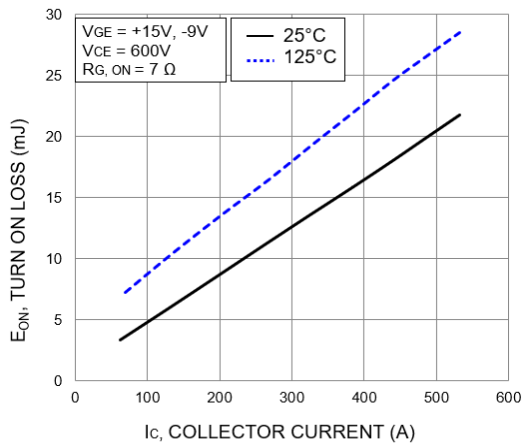


Figure 24. Typical Turn On Loss vs. I_C

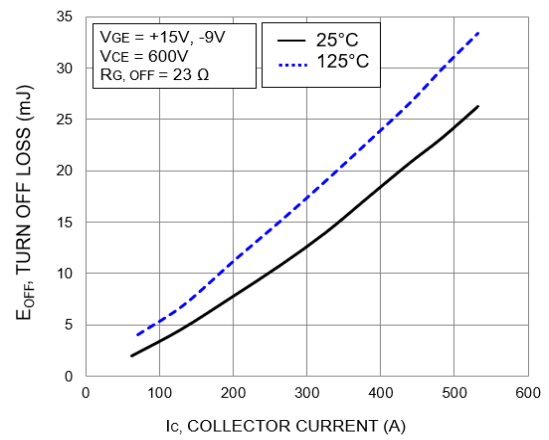


Figure 25. Typical Turn Off Loss vs. I_C

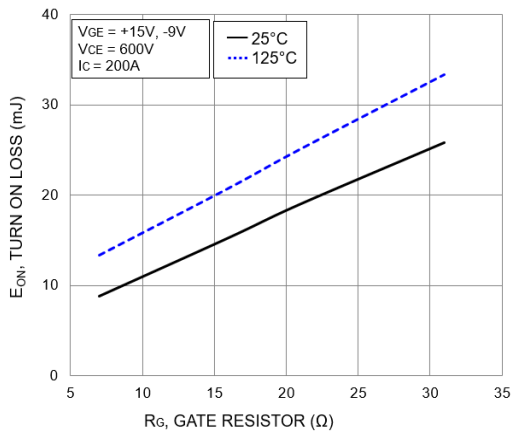


Figure 26. Typical Turn On Loss vs. R_G

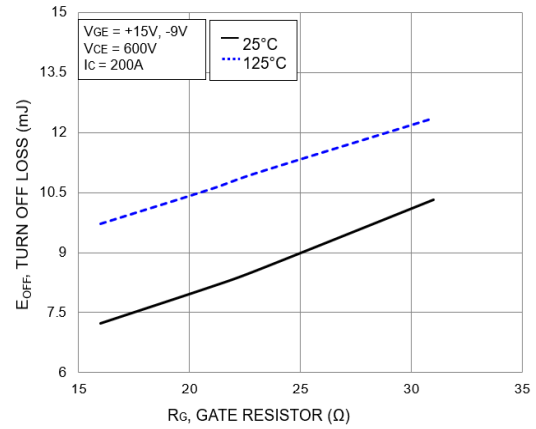


Figure 27. Typical Turn Off Loss vs. R_G

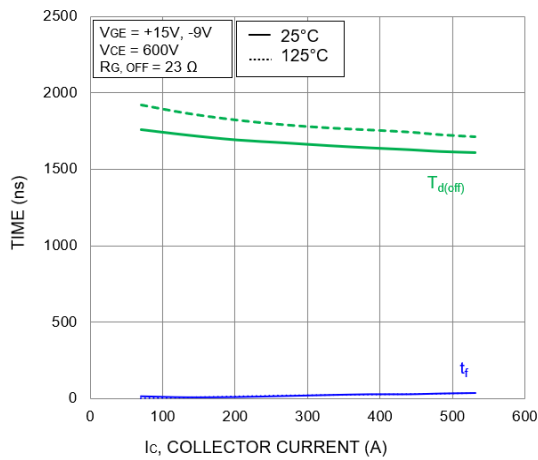


Figure 28. Typical Turn-Off Switching Time vs. I_C

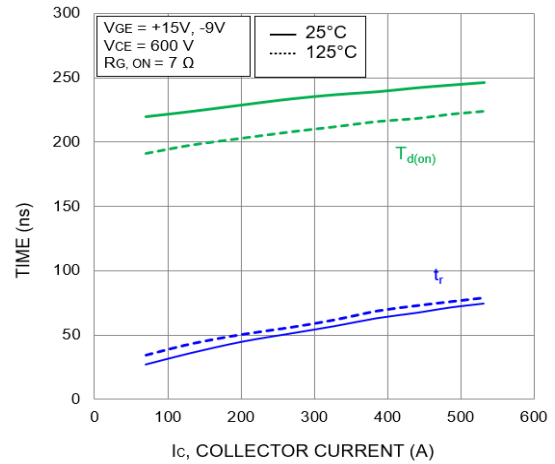


Figure 29. Typical Turn-On Switching Time vs. I_C

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – T1 || D5 OR T4 || D6

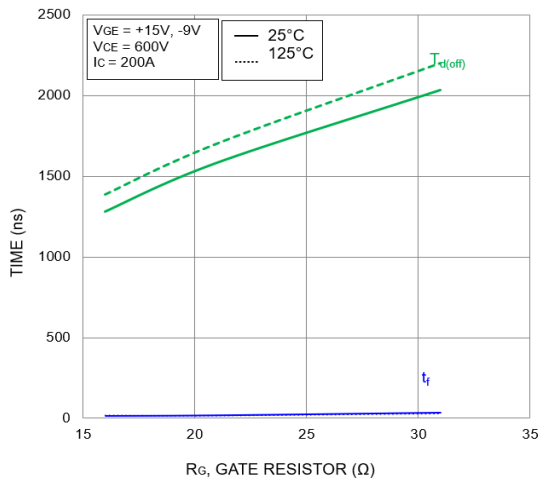


Figure 30. Typical Turn-Off Switching Time vs. R_G

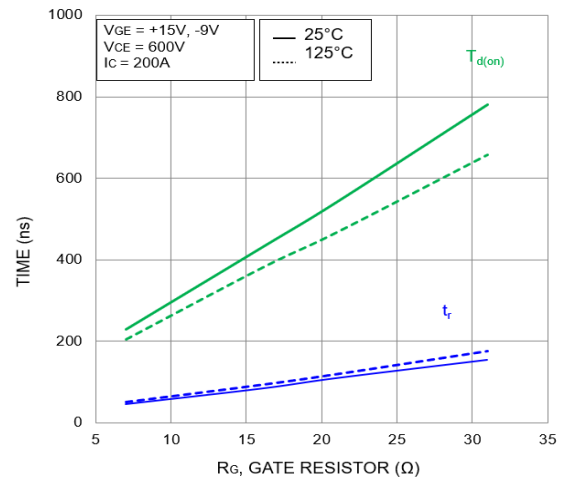


Figure 31. Typical Turn-On Switching Time vs. R_G

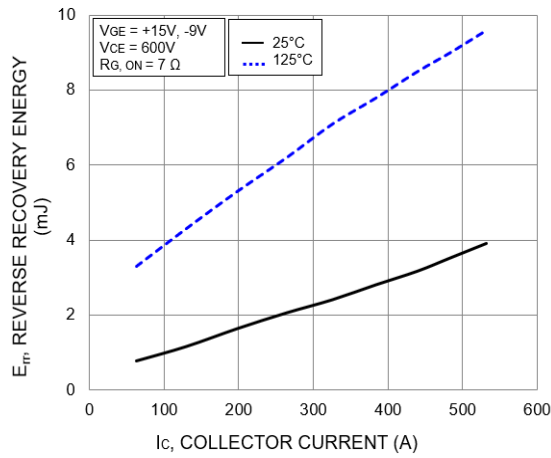


Figure 32. Typical Reverse Recovery Energy Loss vs. I_C

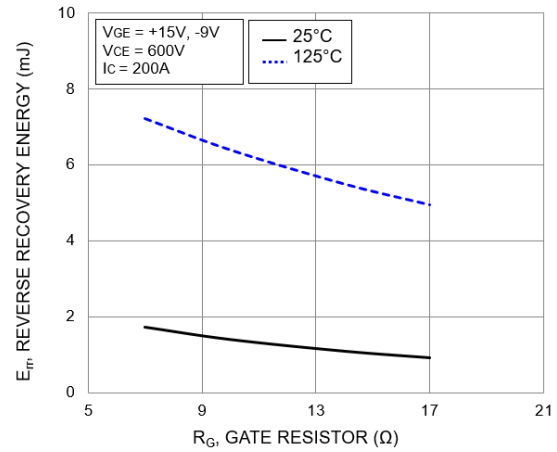


Figure 33. Typical Reverse Recovery Energy Loss vs. R_G

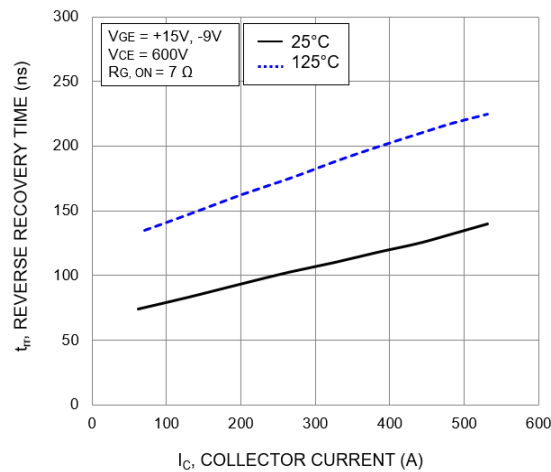


Figure 34. Typical Reverse Recovery Time vs. I_C

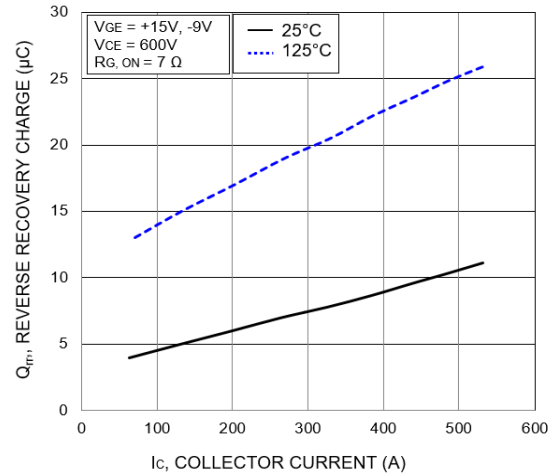


Figure 35. Typical Reverse Recovery Charge vs. I_C

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – T1 || D5 OR T4 || D6

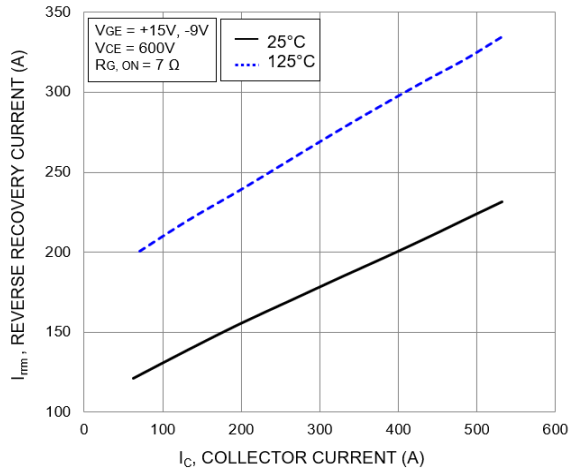


Figure 36. Typical Reverse Recovery Current vs. I_c

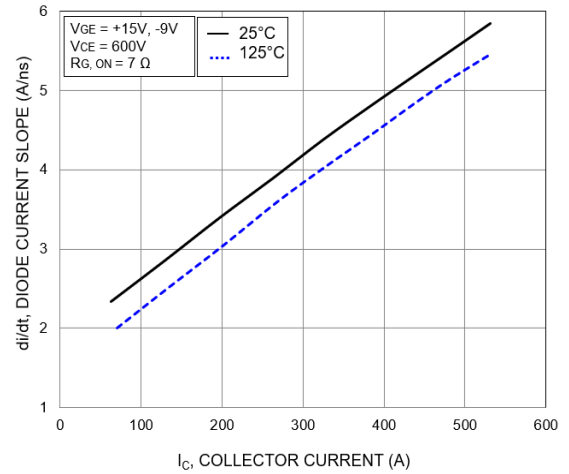


Figure 37. Typical di/dt vs. I_c

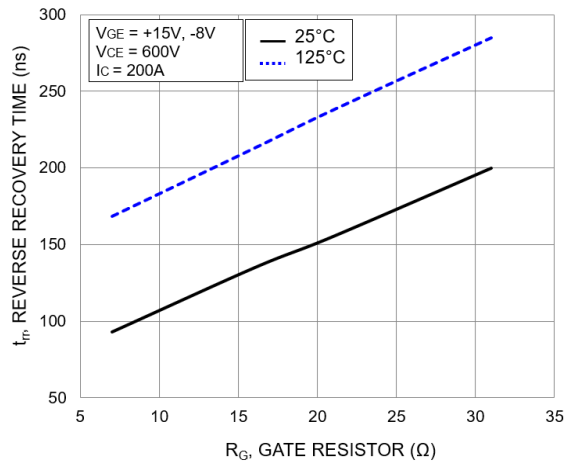


Figure 38. Typical Reverse Recovery Time vs. R_G

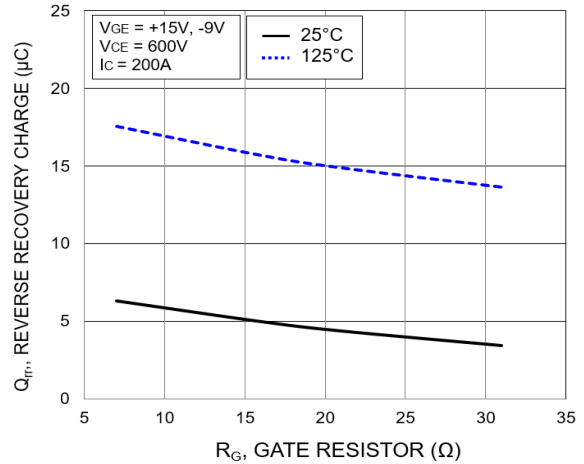


Figure 39. Typical Reverse Recovery Charge vs. R_G

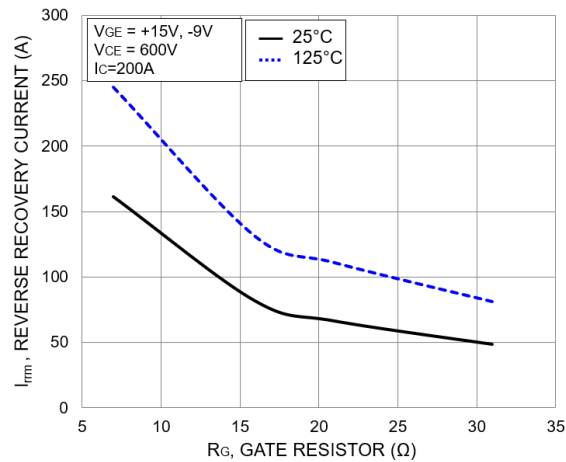


Figure 40. Typical Reverse Recovery Peak Current vs. R_G

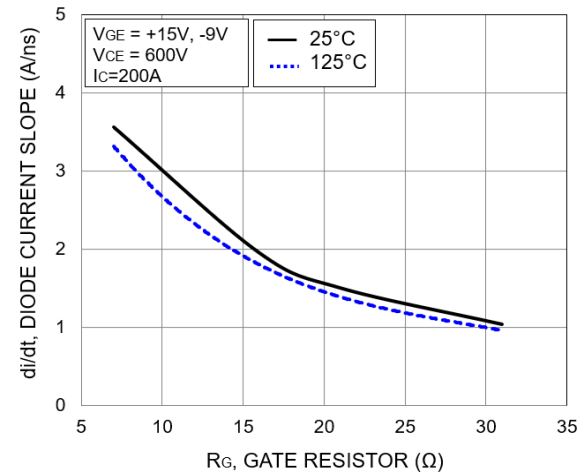


Figure 41. Typical di/dt vs. R_G

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – T2 || D3 + D4 OR T3 || D1 + D2

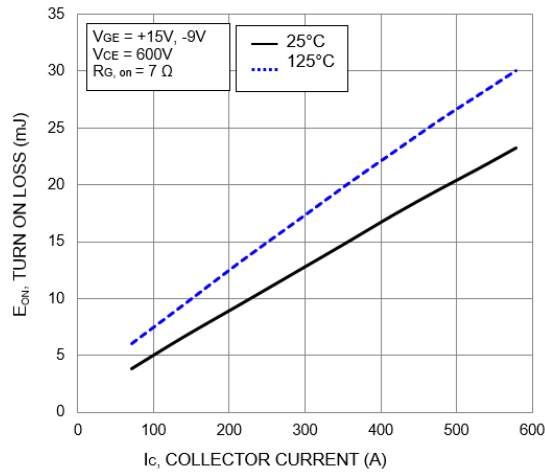


Figure 42. Typical Turn On Loss vs. I_c

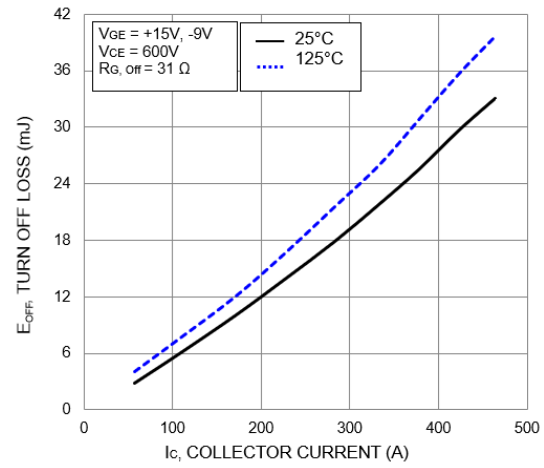


Figure 43. Typical Turn Off Loss vs. I_c

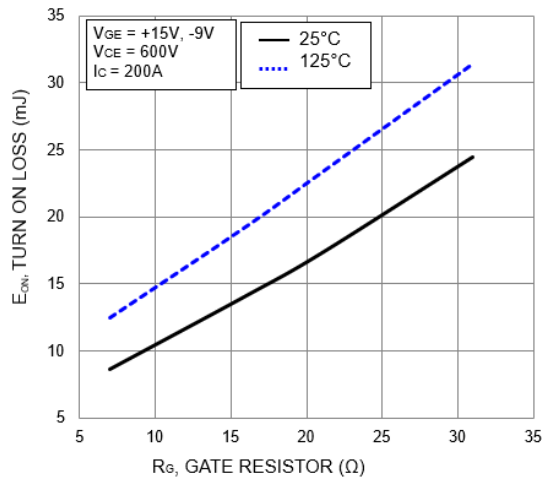


Figure 44. Typical Turn On Loss vs. R_G

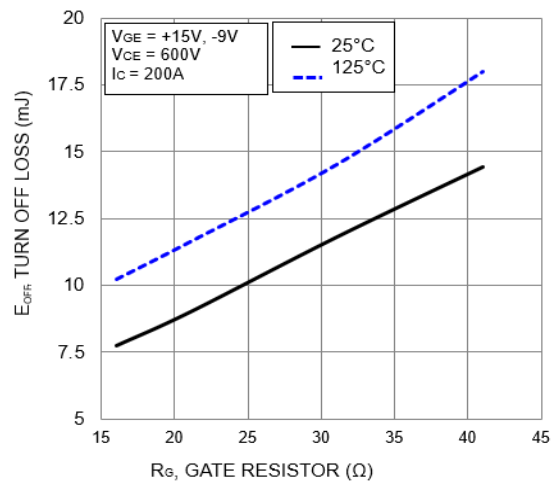


Figure 45. Typical Turn Off Loss vs. R_G

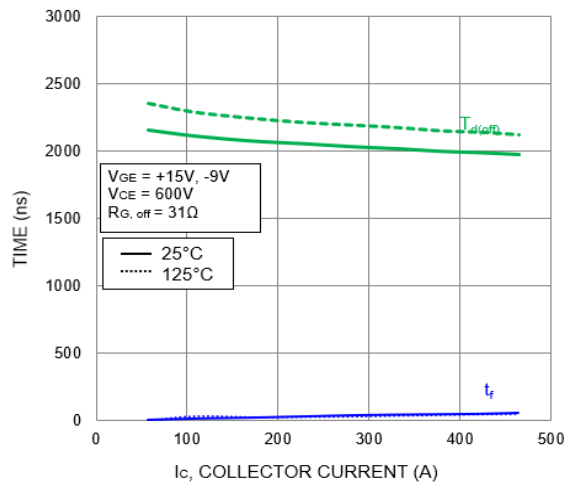


Figure 46. Typical Turn-Off Switching Time vs. I_c

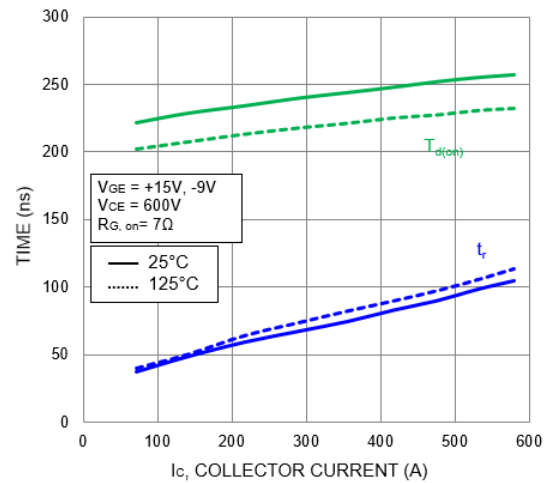


Figure 47. Typical Turn-On Switching Time vs. I_c

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – T2 || D3 + D4 OR T3 || D1 + D2

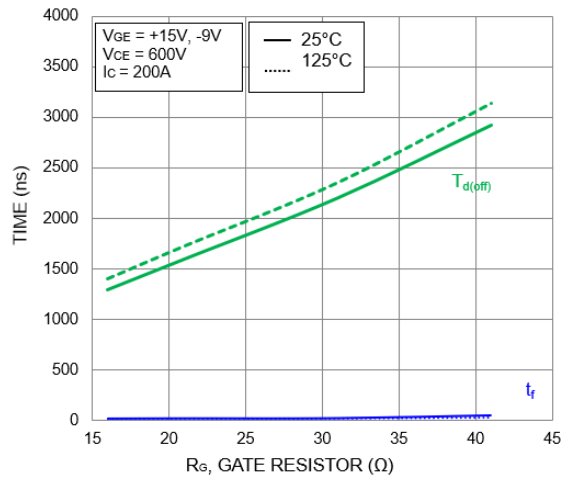


Figure 48. Typical Turn-Off Switching Time vs. R_G

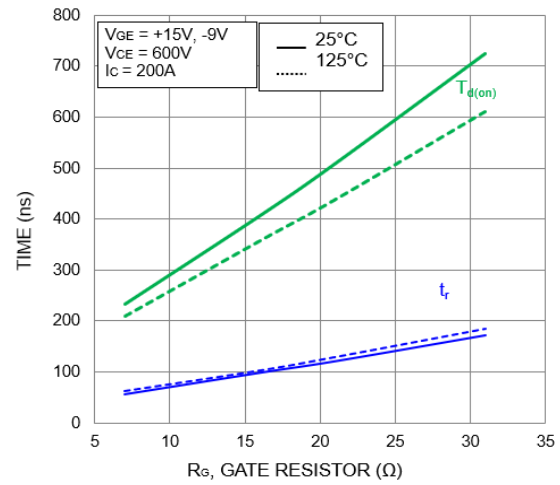


Figure 49. Typical Turn-On Switching Time vs. R_G

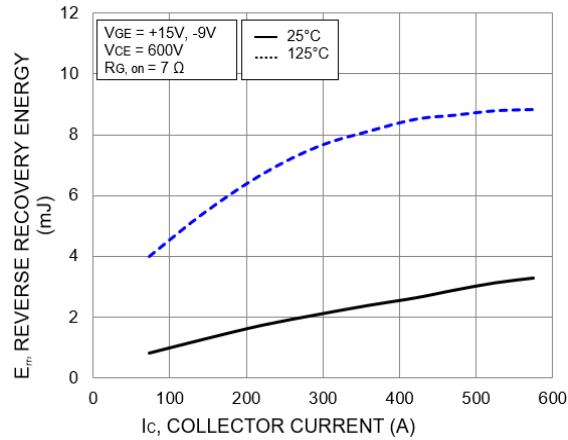


Figure 50. Typical Reverse Recovery Energy Loss vs. I_C

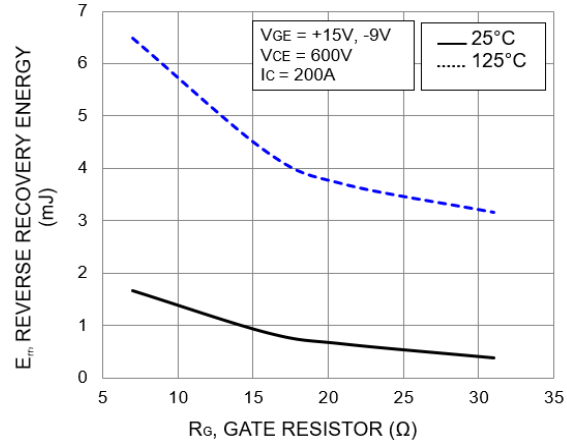


Figure 51. Typical Reverse Recovery Energy Loss vs. R_G

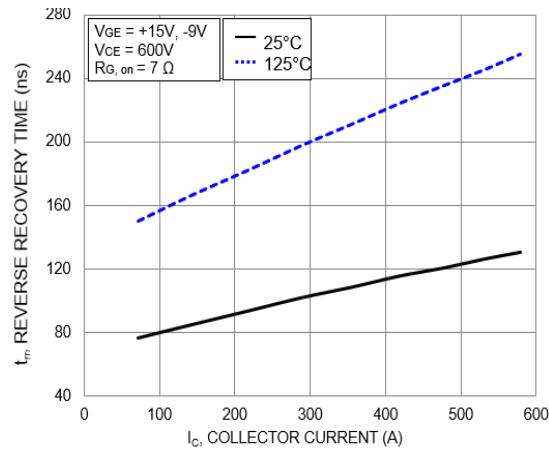


Figure 52. Typical Reverse Recovery Time vs. I_C

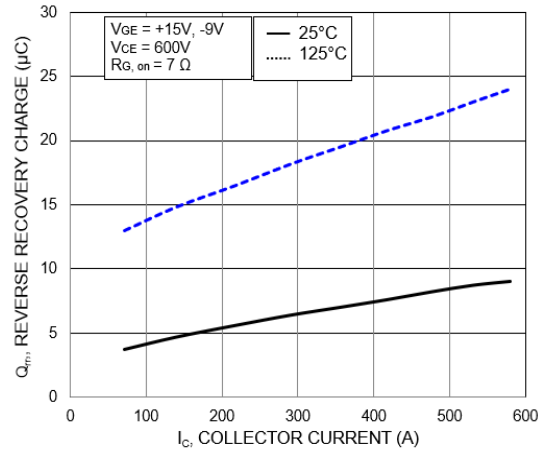


Figure 53. Typical Reverse Recovery Charge vs. I_C

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

TYPICAL CHARACTERISTICS – T2 || D3 + D4 OR T3 || D1 + D2

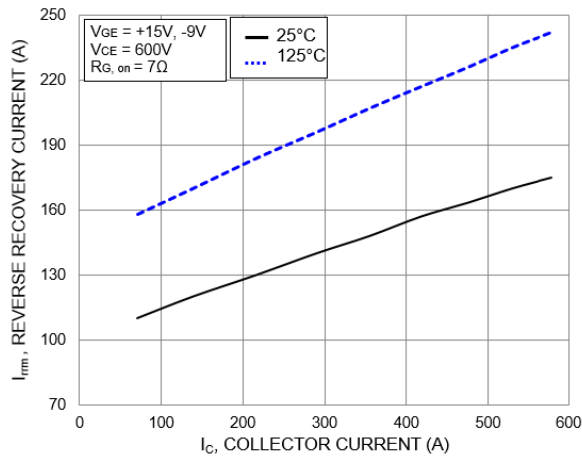


Figure 54. Typical Reverse Recovery Current vs. I_c

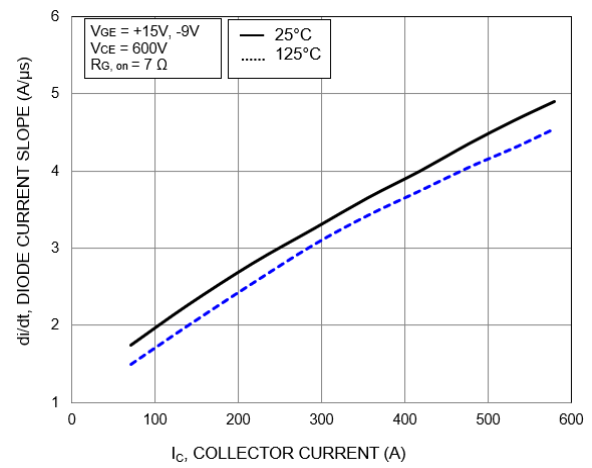


Figure 55. Typical di/dt vs. I_c

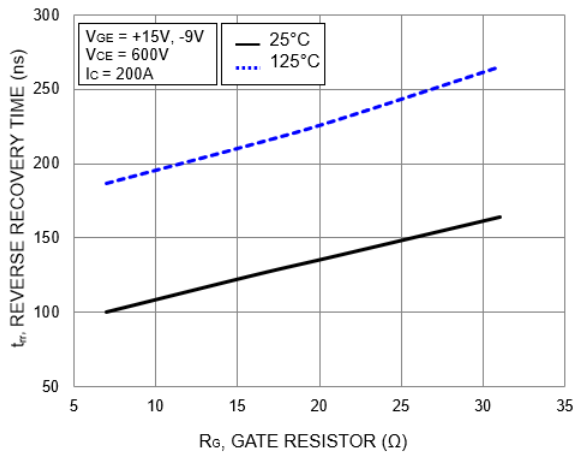


Figure 56. Typical Reverse Recovery Time vs. R_G

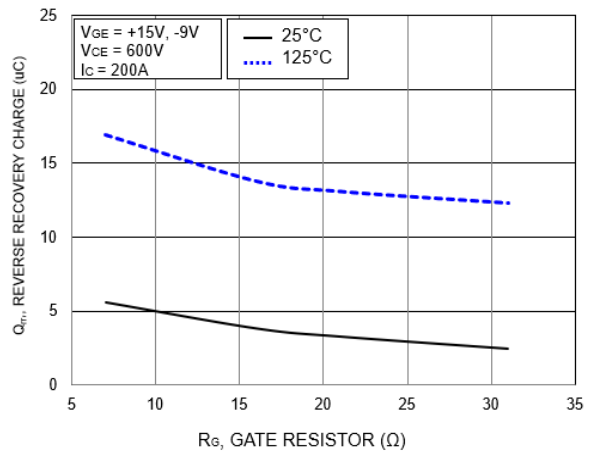


Figure 57. Typical Reverse Recovery Charge vs. R_G

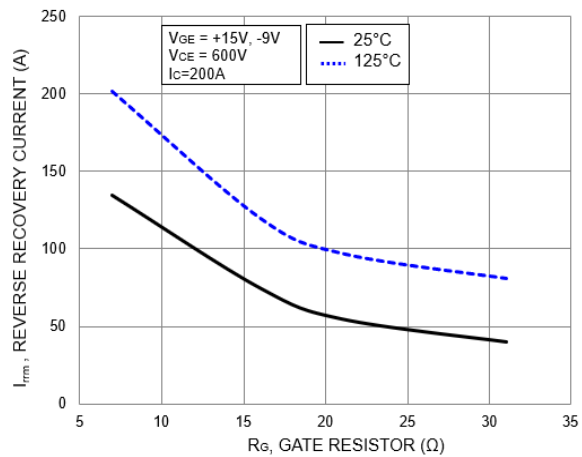


Figure 58. Typical Reverse Recovery Peak Current vs. R_G

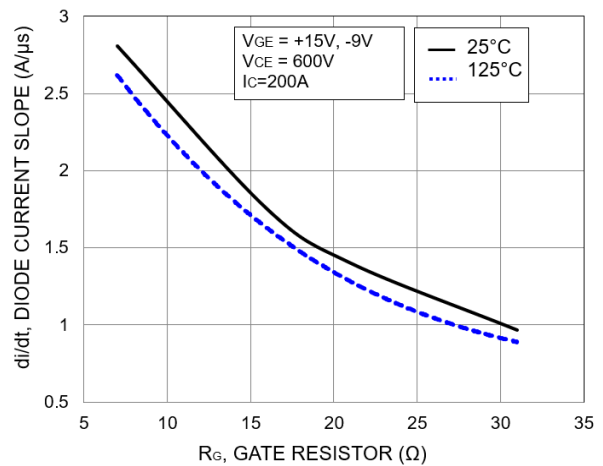


Figure 59. Typical di/dt vs. R_G

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

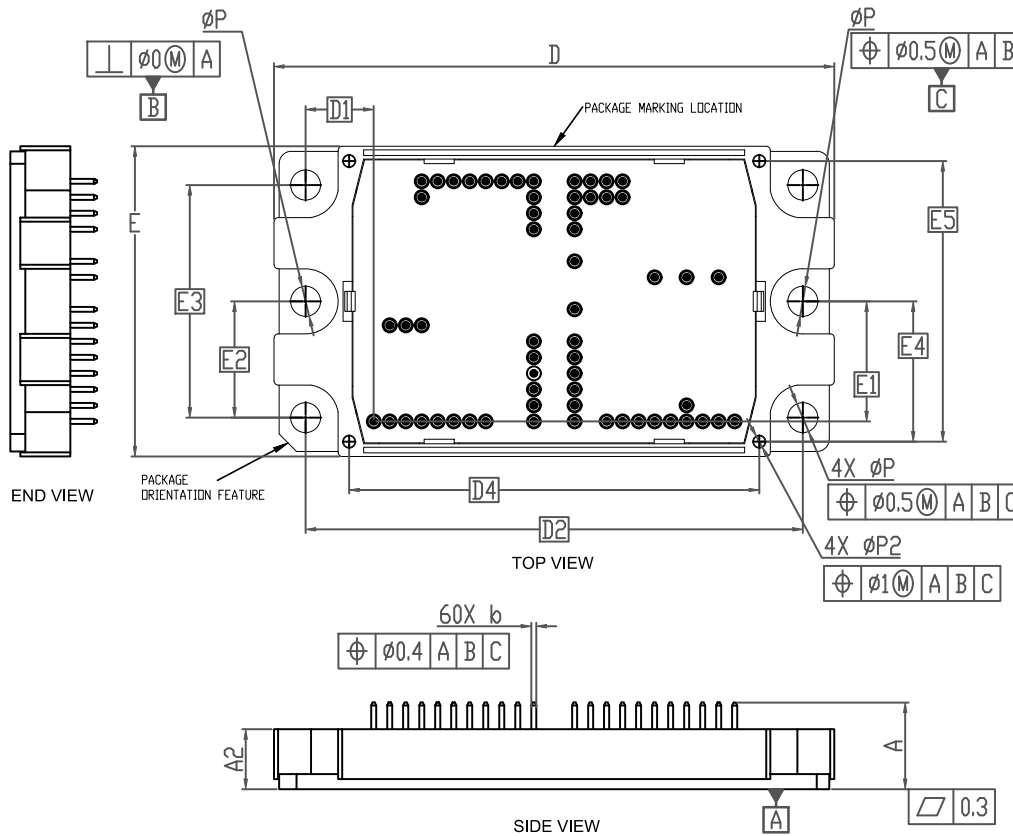
PACKAGE DIMENSIONS

PIM60 112.00x62.00x12.00
CASE 180CY
ISSUE O

DATE 30 JUL 2024

NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5
2. All dimensions are in millimeters.
3. Pin-grid is 3.2mm.
4. Package marking is located on the side opposite the package orientation feature.
5. The pins are gold-plated solder pin.



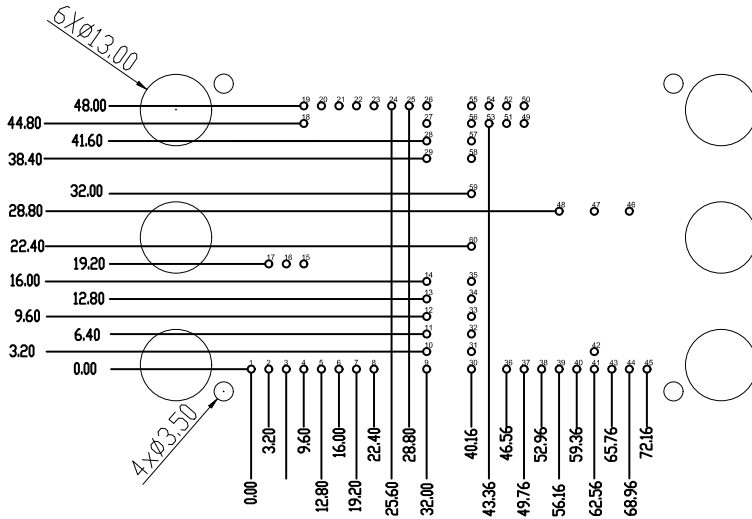
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	17.00	17.40	17.80
A2	11.70	12.00	12.30
b	0.95	1.00	1.05
D	111.60	112.00	112.40
D1	13.62 BSC		
D2	99.40 BSC		
D4	82.00 BSC		
E	61.60	62.00	62.40
E1	24.00 BSC		
E2	23.25 BSC		
E3	46.50 BSC		
E4	28.05 BSC		
E5	56.10 BSC		
P	5.90	6.00	6.10
P2	2.20	2.30	2.40

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

PACKAGE DIMENSIONS

PIM60 112.00x62.00x12.00
CASE 180CY
ISSUE O

DATE 30 JUL 2024



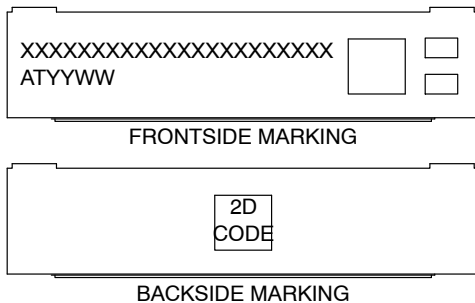
RECOMMENDED MOUNTING PATTERN

* For additional Information on our Pb-Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTE 2:

Pin POSITION								
Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0.00	0.00	24	25.60	48.00	47	62.56	28.80
2	3.20	0.00	25	28.80	48.00	48	56.16	28.80
3	6.40	0.00	26	32.00	48.00	49	49.76	44.80
4	9.60	0.00	27	32.00	44.80	50	49.76	48.00
5	12.80	0.00	28	32.00	41.60	51	46.56	44.80
6	16.00	0.00	29	32.00	38.40	52	46.56	48.00
7	19.20	0.00	30	40.16	0.00	53	43.36	44.80
8	22.40	0.00	31	40.16	3.20	54	43.36	48.00
9	32.00	0.00	32	40.16	6.40	55	40.16	48.00
10	32.00	3.20	33	40.16	9.60	56	40.16	44.80
11	32.00	6.40	34	40.16	12.80	57	40.16	41.60
12	32.00	9.60	35	40.16	16.00	58	40.16	38.40
13	32.00	12.80	36	46.56	0.00	59	40.16	32.00
14	32.00	16.00	37	49.76	0.00	60	40.16	22.40
15	9.60	19.20	38	52.96	0.00			
16	6.40	19.20	39	56.16	0.00			
17	3.20	19.20	40	59.36	0.00			
18	9.60	44.80	41	62.56	0.00			
19	9.60	48.00	42	62.56	3.20			
20	12.80	48.00	43	65.76	0.00			
21	16.00	48.00	44	68.96	0.00			
22	19.20	48.00	45	72.16	0.00			
23	22.40	48.00	46	68.96	28.80			

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

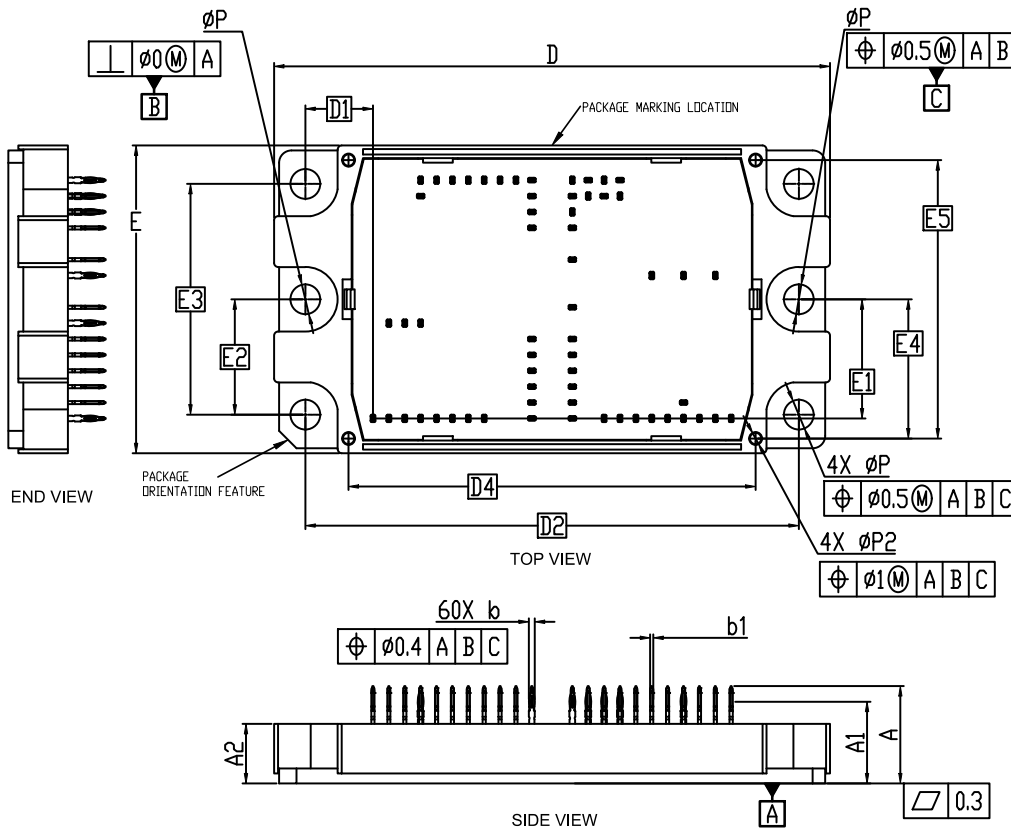
PACKAGE DIMENSIONS

PIM60 112.00x62.00x12.00
CASE 180HY
ISSUE O

DATE 30 JUL 2024

NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5
2. All dimensions are in millimeters.
3. Dimensions b and b1 apply to the plated terminals and are measured at dimension A1
4. Pin-grid is 3.2mm.
5. Package marking is located on the side opposite the package orientation feature.
6. The pins are Sn plated press fit pin.



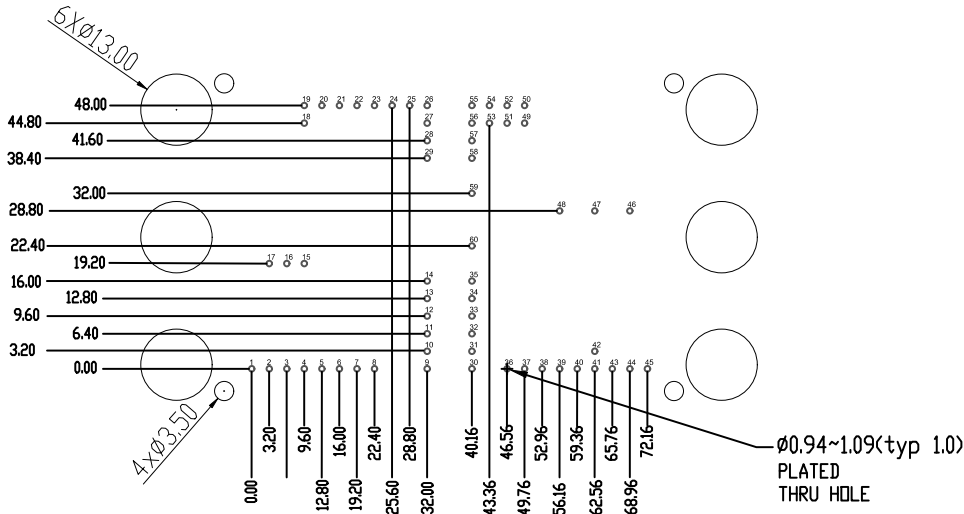
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	19.20	19.60	20.00
A1	16.25	16.45	16.65
A2	11.70	12.00	12.30
b	1.15	1.20	1.25
b1	0.59	0.64	0.69
D	111.60	112.00	112.40
D1	13.62 BSC		
D2	99.40 BSC		
D4	82.00 BSC		
E	61.60	62.00	62.40
E1	24.00 BSC		
E2	23.25 BSC		
E3	46.50 BSC		
E4	28.05 BSC		
E5	56.10 BSC		
P	5.90	6.00	6.10
P2	2.20	2.30	2.40

NXH600N105L7F5S2HG, NXH600N105L7F5P2HG

PACKAGE DIMENSIONS

PIM60 112.00x62.00x12.00
CASE 180HY
ISSUE O

DATE 30 JUL 2024



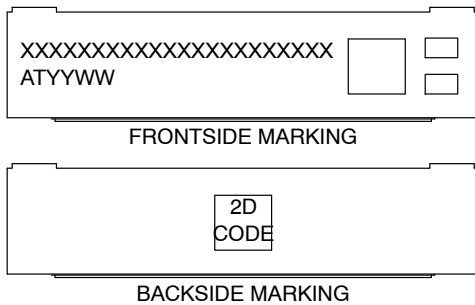
RECOMMENDED MOUNTING PATTERN

* For additional Information on our Pb-Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTE 2:

Pin POSITION								
Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0.00	0.00	24	25.60	48.00	47	62.56	28.80
2	3.20	0.00	25	28.80	48.00	48	56.16	28.80
3	6.40	0.00	26	32.00	48.00	49	49.76	44.80
4	9.60	0.00	27	32.00	44.80	50	49.76	48.00
5	12.80	0.00	28	32.00	41.60	51	46.56	44.80
6	16.00	0.00	29	32.00	38.40	52	46.56	48.00
7	19.20	0.00	30	40.16	0.00	53	43.36	44.80
8	22.40	0.00	31	40.16	3.20	54	43.36	48.00
9	32.00	0.00	32	40.16	6.40	55	40.16	48.00
10	32.00	3.20	33	40.16	9.60	56	40.16	44.80
11	32.00	6.40	34	40.16	12.80	57	40.16	41.60
12	32.00	9.60	35	40.16	16.00	58	40.16	38.40
13	32.00	12.80	36	46.56	0.00	59	40.16	32.00
14	32.00	16.00	37	49.76	0.00	60	40.16	22.40
15	9.60	19.20	38	52.96	0.00			
16	6.40	19.20	39	56.16	0.00			
17	3.20	19.20	40	59.36	0.00			
18	9.60	44.80	41	62.56	0.00			
19	9.60	48.00	42	62.56	3.20			
20	12.80	48.00	43	65.76	0.00			
21	16.00	48.00	44	68.96	0.00			
22	19.20	48.00	45	72.16	0.00			
23	22.40	48.00	46	68.96	28.80			

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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